# 10.0 x 3.2 x 0.5 (mm) ISM Ceramic Chip Antenna (AA066)

## **Engineering Specification**

#### 1. Explanation of Product Number

H 2 U 6 4 6 M H L Q 0 2 0 0



#### Features

- \*Stable and reliable in performances
- \*Low temperature coefficient of frequency
- \*Low profile, compact size
- \*RoHS 2.0 compliance
- \*SMT processes compatible

## 3. Applications

- \*ISM Band system.
- \*RFID system

## 4. Description

Unictron's chip antenna series are specially designed for ISM Band applications. Based on Unictron's proprietary design and processes, this chip antennas has excellent stability and sensitivity to consistently provide high signal reception efficiency.

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Prepared by : Wen Designed by : Ken Checked by : Mike Approved by : Herbert UNIT : mm

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#### **Electrical Specifications (80x40(mm) ground plane)**

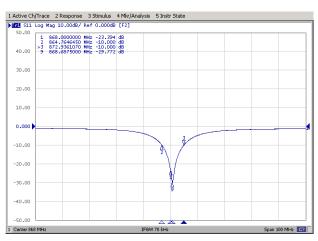
#### 5-1. Electrical Table:

Characteristics		Specifications	Unit	
Outline Dimensions		10x3.2x0.5	mm	
Ground Plane		80x40	mm	
Working Frequency		902~928	MHz	
VSWR (@ center frequency)*		2 Max.		
Characteristic Impedance		50	Ω	
Polarization		Linear Polarization		
Peak Gain	(@015MUz)	0.9 (typical**)	dBi	
Efficiency	(@915MHz)	69 (typical**)	%	

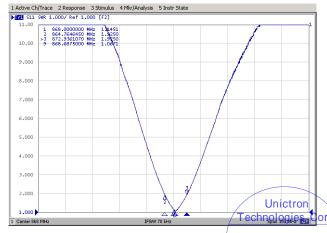
<sup>\*</sup>Center frequency means the frequency with the lowest value in return loss of the chip antenna on the evaluation board..

#### 5-2. Return Loss & VSWR

Return Loss (S<sub>11</sub>)



VSWR (S<sub>11</sub>)



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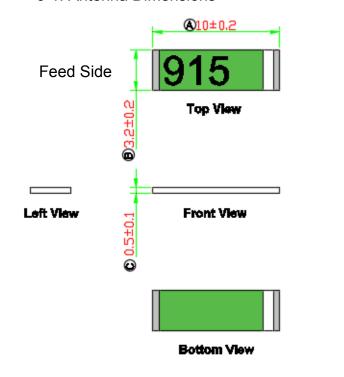
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<sup>\*\*</sup>A typical value is for reference only, not guaranteed.

#### 6. **Antenna Dimensions & Test Board (unit: mm)**

#### 6-1. Antenna Dimensions



#### NOTE:

1.All materials are RoHS 2.0 compliant. 2." A~©" Critical Dimensions. 3."( )" Reference Dimensions.

#### **PIN Definitions**



PIN2

Right View



PIN<sub>1</sub>

## **Top View**

**Bottom View** 

PIN	I		Unictron
Soldering PAD	Signal	Tuning / Ground /	Technologies Corp.

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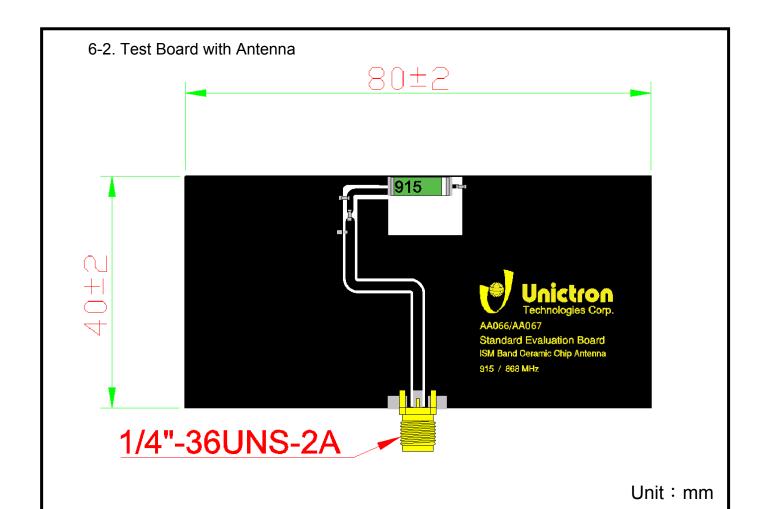
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AND.

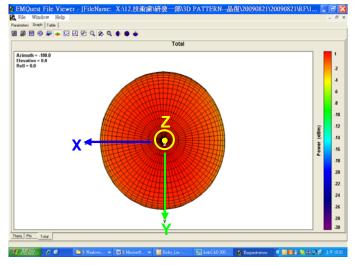
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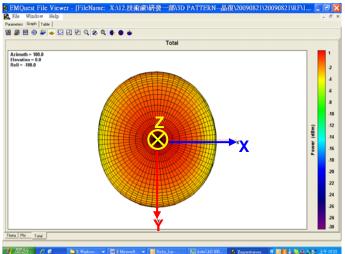
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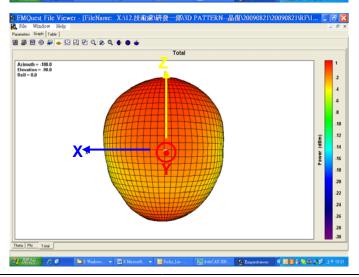
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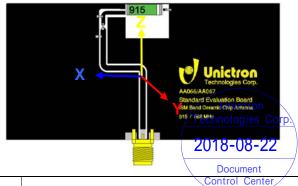
## 7. Radiation Pattern (80x40(mm) ground plane)

7-1. 3D Gain Pattern (Radiation Pattern at 915 MHz)











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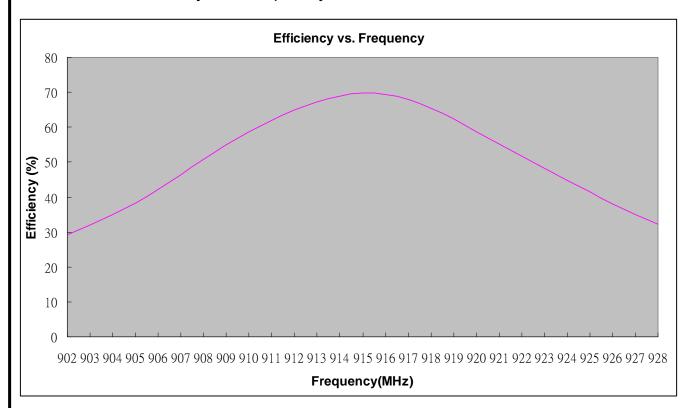
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## 7-2. 3D Efficiency Table

Frequency(MHz)	902	903	904	905	906	907	908	909	910	911	912	913	914	915
Efficiency (dB)	-5.33	-4.96	-4.57	-4.17	-3.74	-3.33	-2.95	-2.61	-2.31	-2.08	-1.87	-1.73	-1.62	-1.56
Efficiency (%)	29.29	31.93	34.91	38.31	42.22	46.45	50.71	54.87	58.73	61.95	65.04	67.18	68.94	69.78
Gain (dBi)	-2.75	-2.35	-2	-1.62	-1.2	-0.77	-0.4	-0.07	0.21	0.43	0.63	0.77	0.87	0.92

Frequency(MHz)	916	917	918	919	920	921	922	923	924	925	926	927	928
Efficiency (dB)	-1.59	-1.68	-1.84	-2.06	-2.31	-2.58	-2.86	-3.16	-3.48	-3.82	-4.19	-4.56	-4.92
Efficiency (%)	69.33	67.94	65.48	62.29	58.73	55.18	51.79	48.33	44.85	41.5	38.08	34.98	32.21
Gain (dBi)	0.88	0.79	0.62	0.4	0.12	-0.16	-0.46	-0.75	-1.11	-1.46	-1.84	-2.24	-2.57

#### 7-3. 3D Efficiency vs. Frequency



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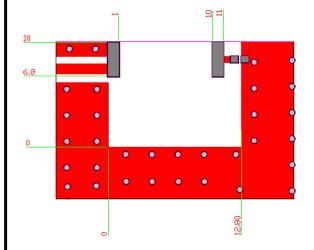
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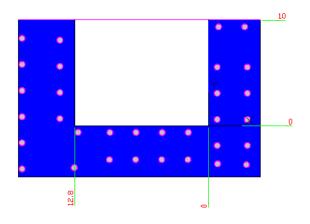
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#### 8. Layout Guide:

#### a. Solder Land Pattern:

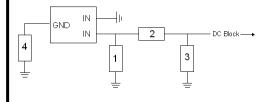
Land pattern for soldering (black marking areas) is as shown below. Matching circuit is needed for good performance, when customer's device is different.





#### b. Matching circuit:

(Center frequency is about 915 MHz @ 80 x 40 mm<sup>2</sup> Evaluation Board)



System Matching Circuit Component							
Location	Description Vendor Tolerance						
1	N/A*	-	-				
2	0Ω*	(0402)	-				
3	5.0pF*	Murata (0402)	±0.05 pF				
4	10pF*	Murata (0402)	±5 %				

<sup>\*</sup>Typical reference values which may need to be changed when circuit boards or part vendors are different.

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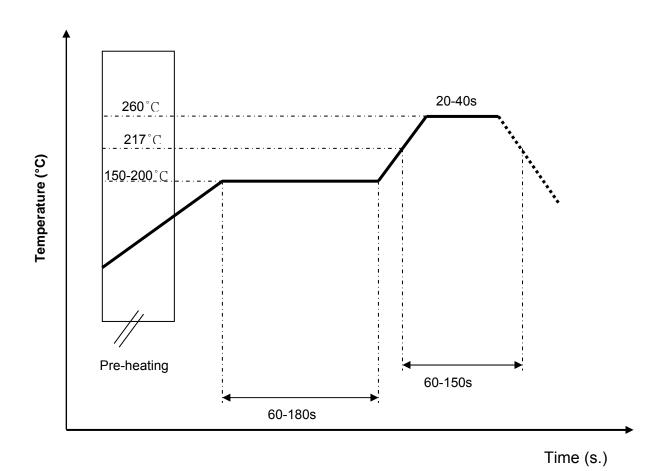
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## 9. Soldering Conditions:

a. Typical Soldering Profile for Lead-free Process



## 10. Reminders for users of Unictron's chip antennas

- a. Since Unictron's chip antennas are made of ceramic materials which show different rigidity than circuit board materials, bending of circuit board at the locations where chip antennas are mounted may cause the cracking of solder joints or antenna itself.
- b. Any connecting strip which will be cut off at PCB assembly process shall be located away from the installation site of chip antenna. Punching of the connecting strip may cause severe bending of the circuit board and cracking of solder joint or chip antenna itself may occur.
- c. Be cautious when ultrasonic welding process needs to be used near the locality of chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.



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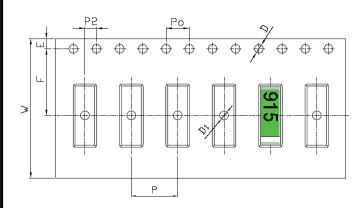
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# 11. Packing:

(1) Quantity/Reel: 6000pcs/Reel

(2) Plastic tape:

a. Tape Drawing



#### b. Tape Dimensions (unit: mm)

Feature	Specifications	Tolerances
W	24.00	±0.30
Р	8.00	±0.10
E	1.75	±0.10
F	11.50	±0.10
P2	2.00	±0.10
D	1.50	+0.10 0.00
D1	1.50	±0.10
Po	4.00	±0.10
10Po	40.00	±0.20

## 12. Operating & Storage Conditions

#### 12-1. Operating

(1) Maximum Input Power: 2 W

(2) Operating Temperature: -40°C to 85°C

(3) Relative Humidity: 10% to 70%

#### 12-2. Storage (sealed)

(1) Storage Temperature: -5°C to 40°C

(2) Relative Humidity: 20% to 70%

(3) Shelf Life: 1 year

#### 12-3. Storage (unsealed)

Meet the criteria of J-STD-033 MSL2a

# 12-4. Storage (After mounted on customer's PCB with SMT process) hictron

(1) Storage Temperature: -40°C to 85°C

(2) Relative Humidity: 10% to 70%

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#### 13. Notice

(1) Installation Guide:

Please refer to Unictron's application note "General guidelines for the installation of Unictron's chip antennas" for further information.

(2) All specifications are subject to change without notice.

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